

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the present invention.

Listing of Claims

1-8. (CANCELLED)

9. (CURRENTLY AMENDED) A substrate cleaning method for cleaning a substrate by bringing a brush into contact with [[a]] the substrate while rotating the same, and by spraying liquid droplets from a two-fluid nozzle onto the substrate, wherein

the brush and the two-fluid nozzle are moved radially outward relative to a center of the substrate, while a cleaning position of the two-fluid nozzle is kept nearer to the center of the substrate than a cleaning position of the brush,

the cleaning position of the brush and the cleaning position of the two-fluid nozzle are moved in directions opposite to each other, and

the cleaning position of the two-fluid nozzle is moved radially outward to a periphery of the substrate relative to the center of the substrate to areas where the brush has been in contact with the substrate.

10. (CURRENTLY AMENDED) The substrate cleaning method according to claim 9, wherein

the brush is brought into contact with the center of the substrate, while spraying liquid droplets from the two-fluid nozzle onto the substrate, and the cleaning position of the brush is started to move radially outward from the center of the substrate, and thereafter the cleaning position of the two-fluid nozzle is positioned above the center of the substrate to move radially outward from the center of the substrate.

11. (ORIGINAL) The substrate cleaning method according to claim 9 or 10, wherein after the brush is separated from the substrate at a peripheral part thereof, the cleaning position of the two-fluid nozzle is moved to a position above a portion with which the brush had been in contact immediately before the brush was separated therefrom.

12. (CANCELED)

13. (PREVIOUSLY PRESENTED) The substrate cleaning method according to claim 9 or 10, wherein

a moving speed of the cleaning position of the brush relative to the substrate and a moving speed of the cleaning position of the two-fluid nozzle relative to the substrate are reduced, as the cleaning position of the brush and the cleaning position of the nozzle move radially outward from the center of the substrate.

14. (CURRENTLY AMENDED) [[The]] A substrate cleaning method according to claim 9 or 10 for cleaning a substrate by bringing a brush into contact with the substrate while rotating the same, and by spraying liquid droplets from a two-fluid nozzle onto the substrate, wherein

the brush and the two-fluid nozzle are moved radially outward relative to a center of the substrate, while a cleaning position of the two-fluid nozzle is kept nearer to the center of the substrate than a cleaning position of the brush,

a moving speed of the cleaning position of the two-fluid nozzle relative to the substrate is higher than a moving speed of the cleaning position of the brush relative to the substrate, and a difference between a distance from the center of the substrate to the cleaning position of the brush and a distance from the center of the substrate to the cleaning position of the two-fluid nozzle becomes gradually smaller, as the cleaning position of the brush approaches a peripheral part of the substrate.

15. (CURRENTLY AMENDED) A medium for recording a program that allows a computer to execute the procedures of bringing a brush into contact with a substrate while rotating the same, and spraying liquid droplets from a two-fluid nozzle onto the substrate, wherein

the brush and the two-fluid nozzle are moved radially outward relative to a center of the substrate, while a cleaning position of the two-fluid nozzle is kept nearer to the center of the substrate than a cleaning position of the brush,

the cleaning position of the brush and the cleaning position of the two-fluid nozzle are moved in directions opposite to each other, and

the cleaning position of the two-fluid nozzle is moved radially outward to a periphery of the substrate relative to the center of the substrate to areas where the brush has been in contact with the substrate.

16. (CURRENTLY AMENDED) The medium according to claim 15, wherein the program allows a computer to execute the procedure of bringing the brush into contact with the center of the substrate, while spraying liquid droplets from the two-fluid nozzle onto the substrate, and starting the cleaning position of the brush to move radially outward from the center of the substrate, and thereafter positioning the cleaning position of the two-fluid nozzle above the center of the substrate to move the same position radially outward from the center of the substrate.

17. (ORIGINAL) The medium according to claim 15 or 16, wherein the program allows a computer to execute the procedures of separating the brush from the substrate at a peripheral part thereof, and thereafter moving the cleaning position of the two-fluid nozzle to a position above a portion with which the brush had been in contact immediately before the brush was separated therefrom.

18. (CANCELED)

19. (PREVIOUSLY PRESENTED) The medium according to claim 15 or 16, wherein the program allows a computer to execute the procedure of reducing a moving speed of the cleaning position of the brush relative to the substrate and a moving speed of the cleaning position of the two-fluid nozzle relative to the substrate, as the cleaning position of the brush and the cleaning position of the nozzle move radially outward from the center of the substrate.

20. (CURRENTLY AMENDED) The A medium according to claim 15 or 16 for recording a program that allows a computer to execute the procedures of bringing a brush into

contact with a substrate while rotating the same, and spraying liquid droplets from a two-fluid nozzle onto the substrate, wherein

the brush and the two-fluid nozzle are moved radially outward relative to a center of the substrate, while a cleaning position of the two-fluid nozzle is kept nearer to the center of the substrate than a cleaning position of the brush,

the program allows a computer to execute the procedure of controlling a moving speed of the cleaning position of the two-fluid nozzle relative to the substrate to be higher than a moving speed of the cleaning position of the brush relative to the substrate, and

a difference between a distance from the center of the substrate to the cleaning position of the brush and a distance from the center of the substrate to the cleaning position of the two-fluid nozzle becomes gradually smaller, as the cleaning position of the brush approaches a peripheral part of the substrate.